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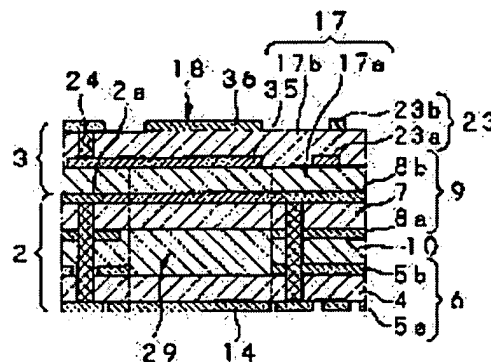
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(54) HIGH-FREQUENCY MODULE SUBSTRATE DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To improve the characteristics of capacitance, and to reduce the size and cost of a high-frequency module substrate device.

SOLUTION: The high-frequency module substrate device comprises a base substrate section 2 that has a main surface as a build-up surface 2a, and a high-frequency circuit section 3 where a passive element is formed inside on the build-up surface 2a of the base substrate section 2. The base substrate section 2 has a wiring non-forming region 29 in a lower layer from a fourth wiring layer 8b. The high-frequency circuit section 3 has a capacitance 18 directly above the wiring non-forming region 29 by forming upper and lower electrode sections 36 and 35 at a position corresponding to the wiring non-forming region 29. As a result, a parasitic capacity that is received from a ground pattern 14 by the capacitance 18 is reduced, and hence the characteristics of the capacitance 18 can be increased.



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